

**INFORMATION DISCLOSURE  
CITATION IN AN  
APPLICATION  
(PTO-1449)**

ATTY. DOCKET NO.  
006217 USA/  
Consilium/Consilium

SERIAL NO.  
09/927,444

APPLICANT  
Nicholas A. WARD et al.

FILING DATE  
August 13, 2001

GROUP  
2125

**U.S. PATENT DOCUMENTS**

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
<i>M</i>	5,975,994	11/02/99	Sandhu et al.			06/11/97
<i>N</i>	6,113,462	09/05/00	Yang			12/18/97
<i>W</i>	6,277,014	08/21/01	Chen et al.			10/09/98

**FOREIGN PATENT DOCUMENTS**


**OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)**


EXAMINER

DATE CONSIDERED

*10/28/04*

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
~	0 397 924 A1	11/22/90	Europe			X	

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	Rocha, Joao and Carlos Ramos. September 12, 1994. "Task Planning for Flexible and Agile Manufacturing Systems." <i>Intelligent Robots and Systems '94. Advanced Robotic Systems and the Real World, IROS '94. Proceedings of the IEEE/RSJ/GI International Conference on Munich, Germany 12-16 Sept. 1994.</i> New York, New York: IEEE. pp. 105-112.
~	March 15, 2002. Office Action for U.S. Serial No. 09/469,227, filed December 22, 1999.
~	March 29, 2002. Office Action for U.S. Serial No. 09/363,966, filed July 29, 1999.
~	June 20, 2002. Office Action for U.S. Serial No. 09/619,044, filed July 19, 2000.
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~	October 23, 2002. Office Action for U.S. Serial No. 09/469,227, filed December 22, 1999.
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~	February 10, 2003. Office Action for U.S. Serial No. 09/619,044, filed July 19, 2000.
~	April 9, 2003. Office Action for U.S. Serial No. 09/928,474, filed August 14, 2001.
~	May 8, 2003. Office Action for U.S. Serial No. 09/637,620, filed August 11, 2000.
~	June 18, 2003. Office Action for U.S. Serial No. 09/655,542, filed September 6, 2000.
~	August 8, 2003. International Search Report for PCT/US03/08513.
~	August 25, 2003. Office Action for U.S. Serial No. 10/100,184, filed March 19, 2002.
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~	December 1, 2003. Office Action for U.S. Serial No. 10/173,108, filed June 18, 2002.
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~	January 23, 2004. International Search Report for PCT/US02/24860.
~	February 2, 2004. Office Action for U.S. Serial No. 09/363,966, filed July 29, 1999.
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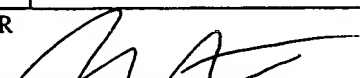
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## U.S. PATENT DOCUMENTS

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<p align="center"><b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION</b></p> <p align="center">(PTO-1449)</p>		<p>ATTY. DOCKET NO. 006217 USA/ Consilium/Consilium</p>	<p>SERIAL NO. 09/927,444</p>
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		<p>FILING DATE August 13, 2001</p>	<p>GROUP 2125</p>
		<p><b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b></p>	
SM	IslamRaja, M. M., C. Chang, J. P. McVittie, M. A. Cappelli, and K. C. Saraswat. May/June 1993. "Two Precursor Model for Low-Pressure Chemical Vapor Deposition of Silicon Dioxide from Tetraethylorthosilicate." <i>J. Vac. Sci. Technol. B</i> , Vol. 11, No. 3, pp. 720-726.		
CM	Kim, Eui Jung and William N. Gill. July 1994. "Analytical Model for Chemical Vapor Deposition of SiO <sub>2</sub> Films Using Tetraethoxysilane and Ozone" (Abstract). <i>Journal of Crystal Growth</i> , Vol. 140, Issues 3-4, pp. 315-326.		
SM	Guo, R.S, A. Chen, C.L. Tseng, I.K. Fong, A. Yang, C.L. Lee, C.H. Wu, S. Lin, S.J. Huang, Y.C. Lee, S.G. Chang, and M.Y. Lee. June 16-17, 1998. "A Real-Time Equipment Monitoring and Fault Detection System." <i>Semiconductor Manufacturing Technology Workshop</i> , pp. 111-121.		
CM	Lantz, Mikkell. 1999. "Equipment and APC Integration at AMD with Workstream." <i>IEEE</i> , pp. 325-327.		
SM	July 15, 2004. Office Action for U.S. Serial No. 10/172,977, filed June 18, 2002.		
CM	August 2, 2004. Office Action for U.S. Serial No. 10/174,377, filed June 18, 2002.		
SM	August 9, 2004. Written Opinion for PCT Serial No. PCT/US02/19063.		
CM	August 18, 2004. International Preliminary Examination Report for PCT Serial No. PCT/US02/19116.		
CM	August 24, 2004. Office Action for U.S. Serial No. 10/135,405, filed May 1, 2002.		
CM	August 25, 2004. Office Action for U.S. Serial No. 09/998,384, filed November 30, 2001.		
SM	September 9, 2004. Written Opinion for PCT Serial No. PCT/US02/21942.		
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SHEET 2 OF 5

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## U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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✓	5,240,552	08/31/93	Yu et al.			12/11/91
✓	5,369,544	11/29/94	Mastrangelo			04/05/93
✓	5,444,837	08/22/95	Bomans et al.			12/29/93
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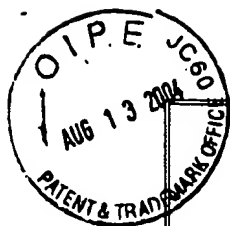


SHEET 3 OF 5

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U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
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~	6,630,741 B1	10/07/03	Lopatin et al.			12/07/01	
~	6,660,633 B1	12/09/03	Lopatin et al.			02/26/02	
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## FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
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~	Tagami, M., A. Furuya, T. Onodera, and Y. Hayashi. 1999. "Layered Ta-nitrides (LTN) Barrier Film by Power Swing Sputtering (PSS) Technique for MOCVD-Cu Damascene Interconnects." <i>IEEE</i> . pp. 635-638.
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✓	April 28, 2004. Written Opinion for PCT/US02/19117.
~	April 29, 2004. Written Opinion for PCT/US02/19061.
~	May 5, 2004. Office Action for U.S. Serial No. 09/943,955, filed August 31, 2001.
~	May 5, 2004. International Preliminary Examination Report for PCT/US01/27406.
~	May 28, 2004. Office Action for U.S. Serial No. 09/943,383, filed August 31, 2001.
~	June 3, 2004. Office Action for U.S. Serial No. 09/928,474, filed August 14, 2001.
~	June 23, 2004. Office Action for U.S. Serial No. 10/686,589, filed October 17, 2003.
✓	June 30, 2004. Office Action for U.S. Serial No. 09/800,980, filed March 8, 2001.
~	July 12, 2004. Office Action for U.S. Serial No. 10/173,108, filed June 8, 2002.

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